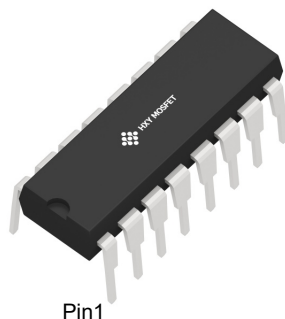




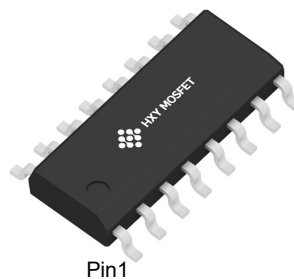
Descriptions

ULN2003 is high-voltage, high-current Seven Darlington arrays each containing seven open collector Darlington pairs with common emitters. Each channel is rated at 500 mA and can withstand peak currents of 600 mA. Suppression diodes are included for inductive load driving. The circuit is designed with a continuous diode, which can be used to drive the relay, stepper motor and other inductive loads. Single channel Darlington tube collector can output 500mA current. Higher output current capability is achieved by connecting Darlington tubes in parallel. The circuit can be widely used in relay driver, lighting driver, display driver (LED), stepper motor driver and logic buffer. It is useful for driving a wide range of loads including relay DC motors, LED display filament lamps, high-power buffers, 5V TTL, CMOS and other industry-standard logical circuit.

This chip is available in DIP-16 or SOP-16 package.



DIP-16



SOP-16

Feature

- Output current 500 mA per driver
- Withstand High Voltage (50V/60V two version)
- Input Pins Compatible to TTL/CMOS Logic Signal
- a Wide Application in Relay Driver

Applications

- Relay Driver
- Lamps Driver
- Display Driver

Ordering Information

Product Model	Package Type	Packing	Packing Qty	Remarks
ULN2003ALN	DIP-16	Tube	1000Pcs/Box	50V
ULN2003ALDTR	SOP-16	Tape	2500Pcs/Reel	50V
ULN2003AN	DIP-16	Tube	1000Pcs/Box	60V
ULN2003ADTR	SOP-16	Tape	2500Pcs/Reel	60V

Circuit Diagram

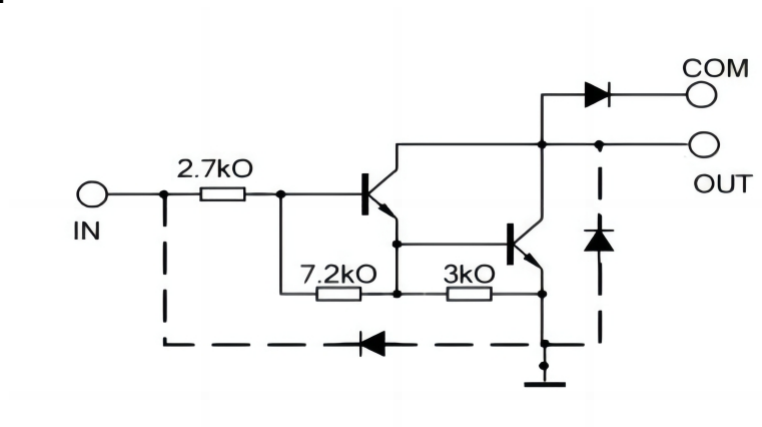


Figure 1 . Circuit Diagram

Pins Configuration

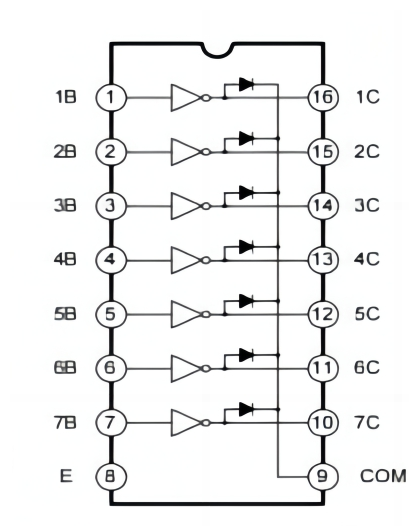


Figure 2. Pins Configuration

Pins Description

No.	Name	Type	Description
1	1B	I	Input 1
2	2B	I	Input 2
3	3B	I	Input 3
4	4B	I	Input 4
5	5B	I	Input 5
6	6B	I	Input 6
7	7B	I	Input 7
8	E	-	Ground
9	COM	-	Common Free Wheeling Diodes
10	7C	O	Output 7
11	6C	O	Output 6
12	5C	O	Output 5
13	4C	O	Output 4
14	3C	O	Output 3
15	2C	O	Output 2
16	1C	O	Output 1



Absolute Maximum Ratings (T_A=25°C)

Parameter		Symbol	Min.	Max.	Unit
Collector-Emitter Voltage（Pin 10~ 16）	60V	V _{CE}	-0.5	60	V
	50V		-0.5	50	
Com Voltage（Pin 9）	60V	V _{COM}		60	V
	50V			50	
Input Voltage（Pin 1~7）		V _I	-0.5	30	V
Collector Peak Current		I _{CP}		500	mA/ch
Output Clamp Current		I _{OK}		500	mA
Emitter Maximum Current		I _{ET}		-2.5	A
Junction-To-Ambient Thermal Resistance	SOP16	θ _{JA}	63		℃/W
	DIP16		50		
Operating Temperature Range		T _{amb}	-40	85	℃
Maximum Junction Temperature		T _J		150	℃
Welding Temperature				260	℃, 10s
Storage Temperature Range		T _{stg}	-60	+150	℃
Power Dissipation	SOP16	P _D	1.28		W
	DIP16		1.5		

Recommended Operating Conditions

(T_A=25°C, unless otherwise noted)

Parameter		Symbol	Conditions	Min.	Max.	Unit
Collector-Emitter Voltage	60V	V _{CE}		0	60	V
	50V			0	50	
Maximum Junction Temperature		T _J			125	°C
Input Voltage		V _{IN}		0	24	V
Input Voltage (Output On)		V _{IN(ON)}	I _{OUT} =400mA, h _{FE} =800	2.5	24	V
Input Voltage (Output Off)		V _{IN(OFF)}		0	0.7	V
Clamp Forward Current		I _F			350	mA
Power Dissipation		P _D	T _A =-85°C		0.325	W



Electrical Characteristics (T_A=25°C)

Parameter	Test Diagrams	Test Conditions	Min.	Typ.	Max.	Unit
V _{I(ON)}	On-State Input Voltage	Figure 11 V _{CE} =2V	I _C =200mA		2.4	V
			I _C =250mA		2.7	
			I _C =300mA		3	
V _{OH}	High-Level Output Voltage After Switching	Figure 17 V _S =50V I _O =300m	60V	VS-50		mV
			50V	VS-50		
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	Figure 10	I _I =250μA, I _C = 100mA	0.9	1.1	V
			I _I =350μA, I _C =200mA	1.0	1.3	
			I _I =500μA, I _C =350mA	1.4	1.6	
I _{CEX}	Collector Cutoff Current	Figure 16	V _{CE} =50V, I _I =0		50	μA
V _F	Clamp Forward Voltage	Figure 15	I _F =350mA	1.7	2	V
I _{I(off)}	Off-State Input Current	Figure 13	V _{CE} =50V, I _C =500μA	50	65	uA
I _I	Input Current	Figure 14	V _I =3.85V	0.93	1.35	mA
h _{FE}	Dc Forward Current Gain	Figure 10	V _{CE} =2V, I _C =350mA	1000		
I _R	Clamp Reverse Current	Figure 12	V _R =50V		50	μA
C _I	Input Capacitance		V _I =0, f= 1MHz	15	25	pF
t _{PLH}	Propagation Delay Time, Low- To High-Level Output	Figure 17		0.25	1	μS
t _{PHL}	Propagation Delay Time, High- To Low-Level Output	Figure 17		0.25	1	μS

Electrical Characteristics (T_A=-40°C ~ 85°C)

Parameter	Test Diagrams	Test Conditions	Min.	Typ.	Max.	Unit
V _{I(ON)}	On-State Input Voltage	Figure 11 V _{CE} =2V	I _C =200mA		2.7	V
			I _C =250mA		2.9	
			I _C =300mA		3	
V _{OH}	High-Level Output Voltage After Switching	Figure 17 V _S =50V I _O =300m	60V	VS-50		mV
			50V	VS-50		
V _{CE(SAT)}	Collector-Emitter Saturation Voltage	Figure 10	I _I =250μA, I _C = 100mA	0.9	1.2	V
			I _I =350μA, I _C =200mA	1.0	1.4	
			I _I =500μA, I _C =350mA	1.4	1.7	
I _{CEX}	Collector Cutoff Current	Figure 16	V _{CE} =50V, I _I =0		98	μA
V _F	Clamp Forward Voltage	Figure 15	I _F =350mA	1.7	2.3	V
I _{I(off)}	Off-State Input Current	Figure 13	V _{CE} =50V, I _C =500μA	30	65	uA
I _I	Input Current	Figure 14	V _I =3.85V	0.93	1.35	mA
I _R	Clamp Reverse Current	Figure 12	V _R =50V		100	μA
C _I	Input Capacitance		V _I =0, f= 1MHz	15	25	pF
t _{PLH}	Propagation Delay Time, Low- To High-Level Output	Figure 17		1.0	10	μS
t _{PHL}	Propagation Delay Time, High- To Low-Level Output	Figure 17		1.0	10	μS



Characteristic Curves

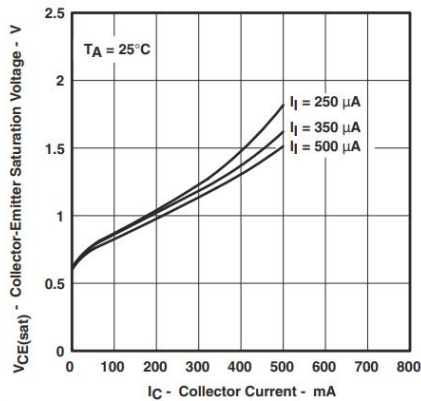


Figure 3. Collector-Emitter Saturation Voltage vs Collector Current

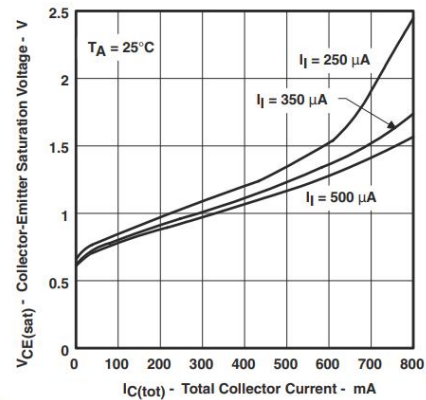


Figure 4. Collector-Emitter Saturation Voltage vs Total Collector Current (Two Darlings in Parallel)

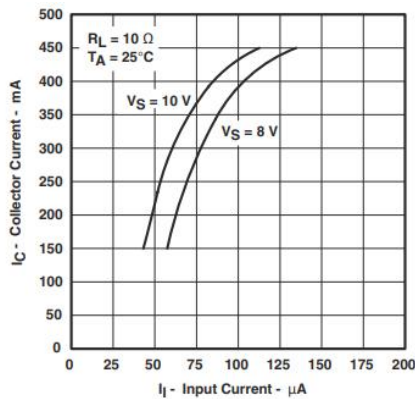


Figure 5. Collector Current vs Input Current

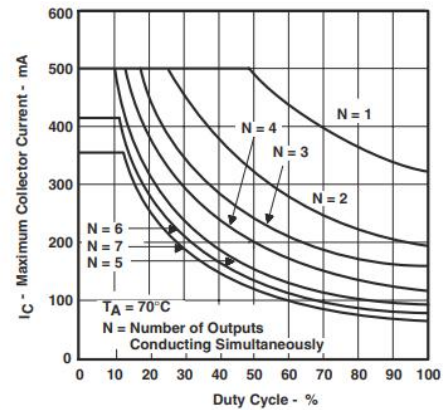


Figure 6. Package Maximum Collector Current vs Duty Cycle

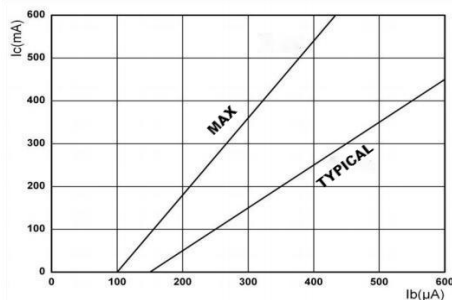


Figure 7. Input Current vs. Input Voltage

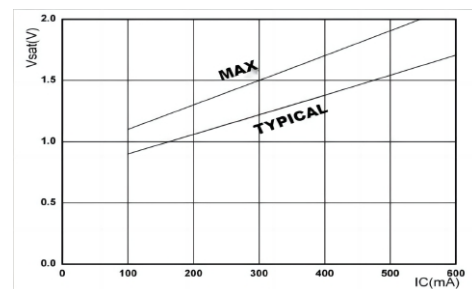


Figure 8. Collector Current vs. Saturation Voltage

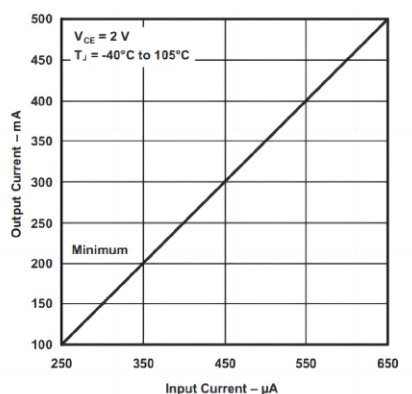


Figure 9. Collector current vs. input current



Test Parameter Diagram

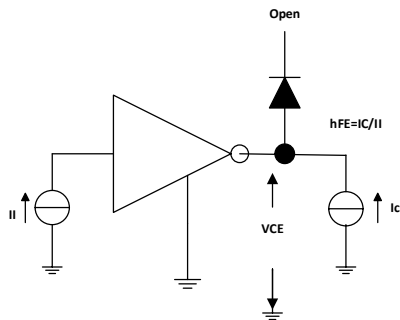


Figure 10. h_{FE} , $V_{CE(sat)}$ Test Circuit

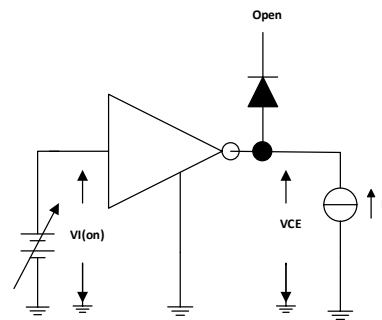


Figure 11. $V_{I(on)}$ Test Circuit

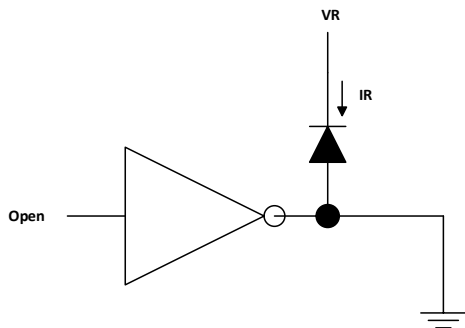


Figure 12. I_R Test Circuit

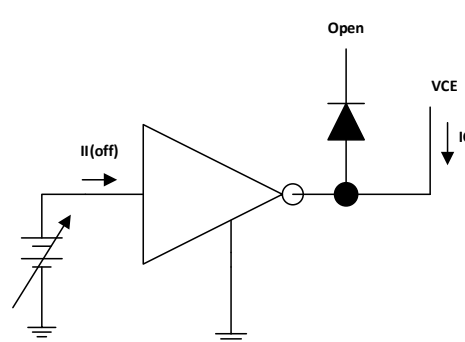


Figure 13. $I_{I(off)}$ Test Circuit

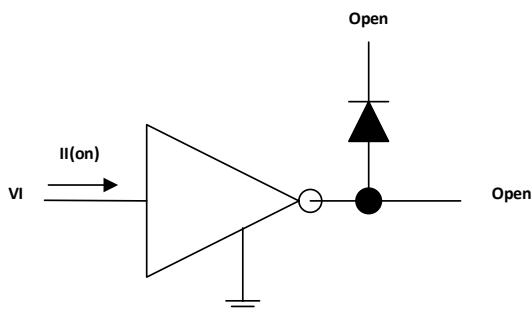


Figure 14. I_I Test Circuit

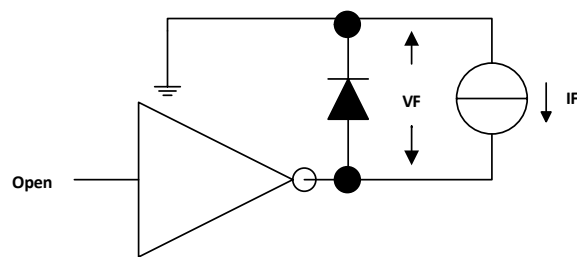


Figure 15. V_F Test Circuit

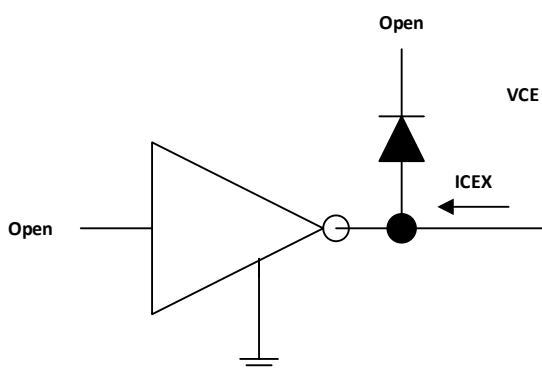


Figure 16. I_{Cex} Test Circuit

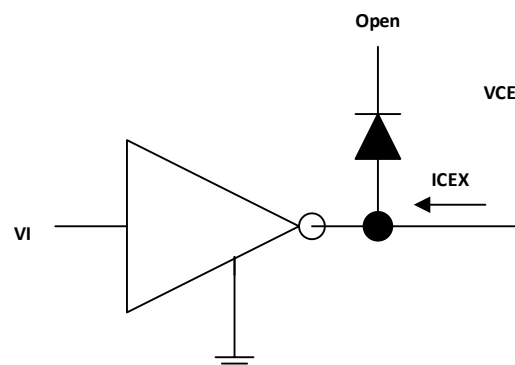
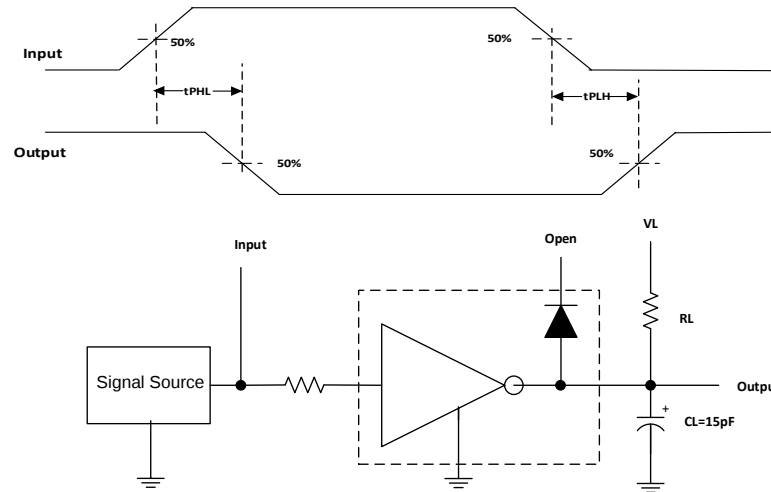


Figure 16. I_{Cex} Test Circuit



Note: The capacitance load in Figure 17. is the parasitic capacitance of the oscilloscope probe.

Figure 17. Propagation Delay-Time Waveforms

Typical applications

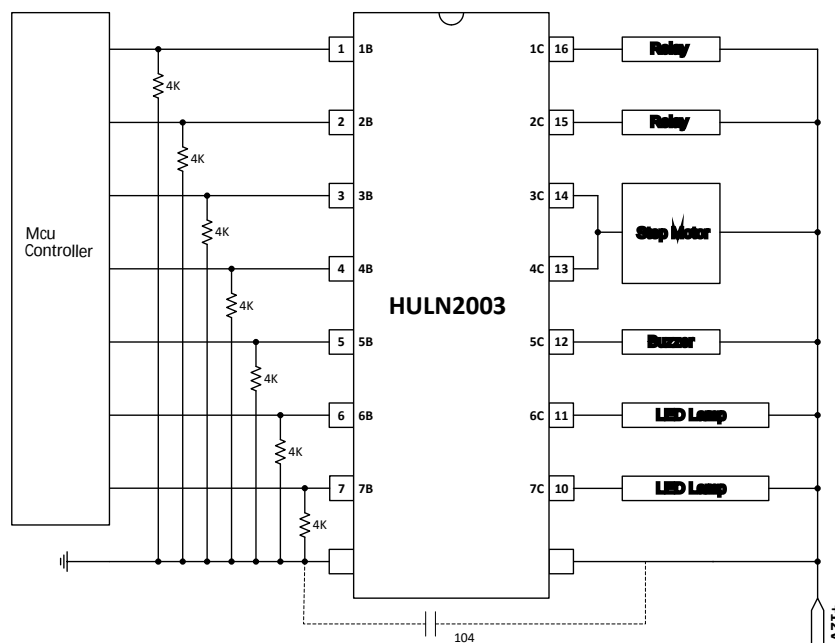


Figure 18. ULN2003 Application Diagram

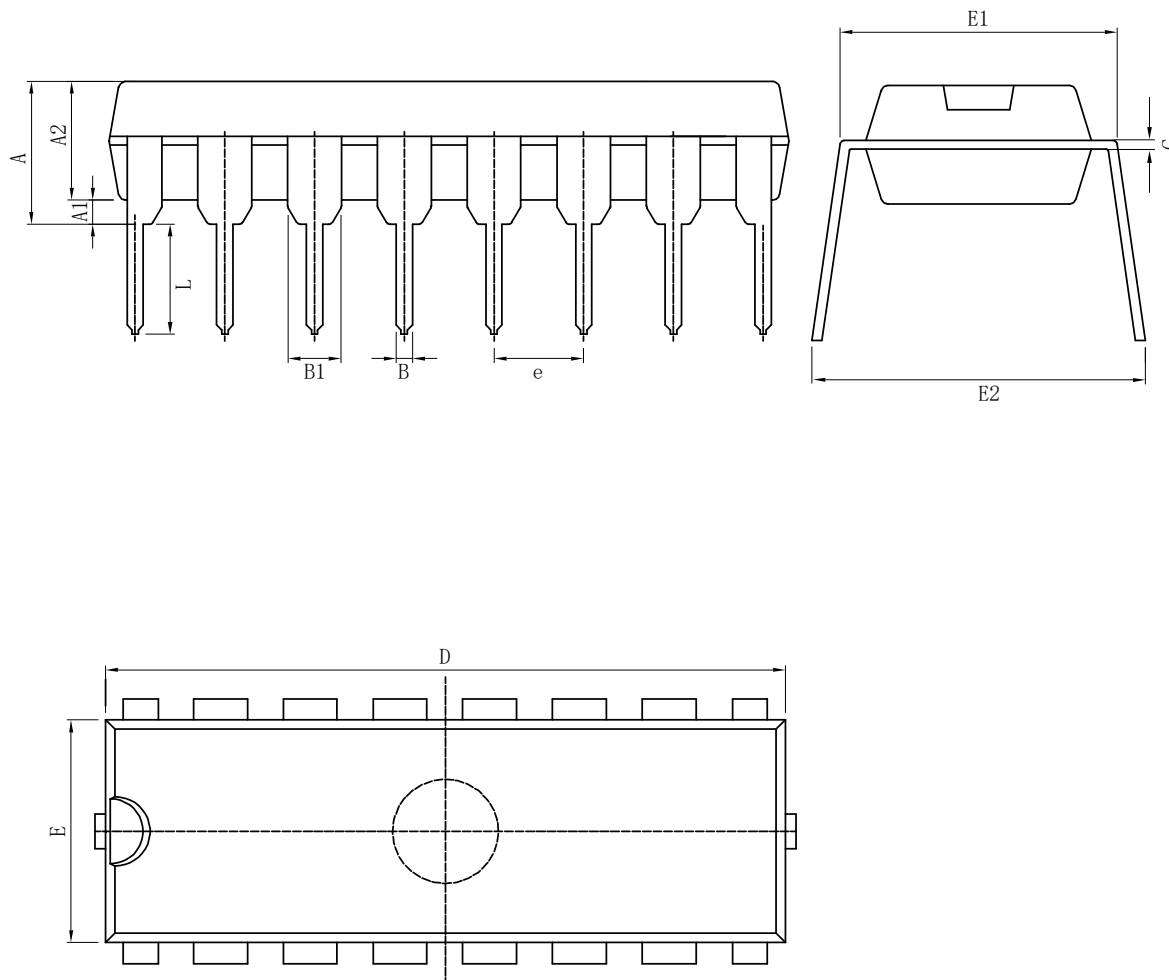
Application Instructions

Considering that some applications use microcontroller with pull-out resistance, the output state of microcontroller is uncertain when it is powered on and the ULN2003 input stage will be affected by the pull-out resistance of microcontroller and the load will be opened. In order to avoid the misaction of load, it is recommended that customers with such application problems connect a 4K pull-down resistance to the ground at the input stage, as shown in the Figure 18.



Package Information

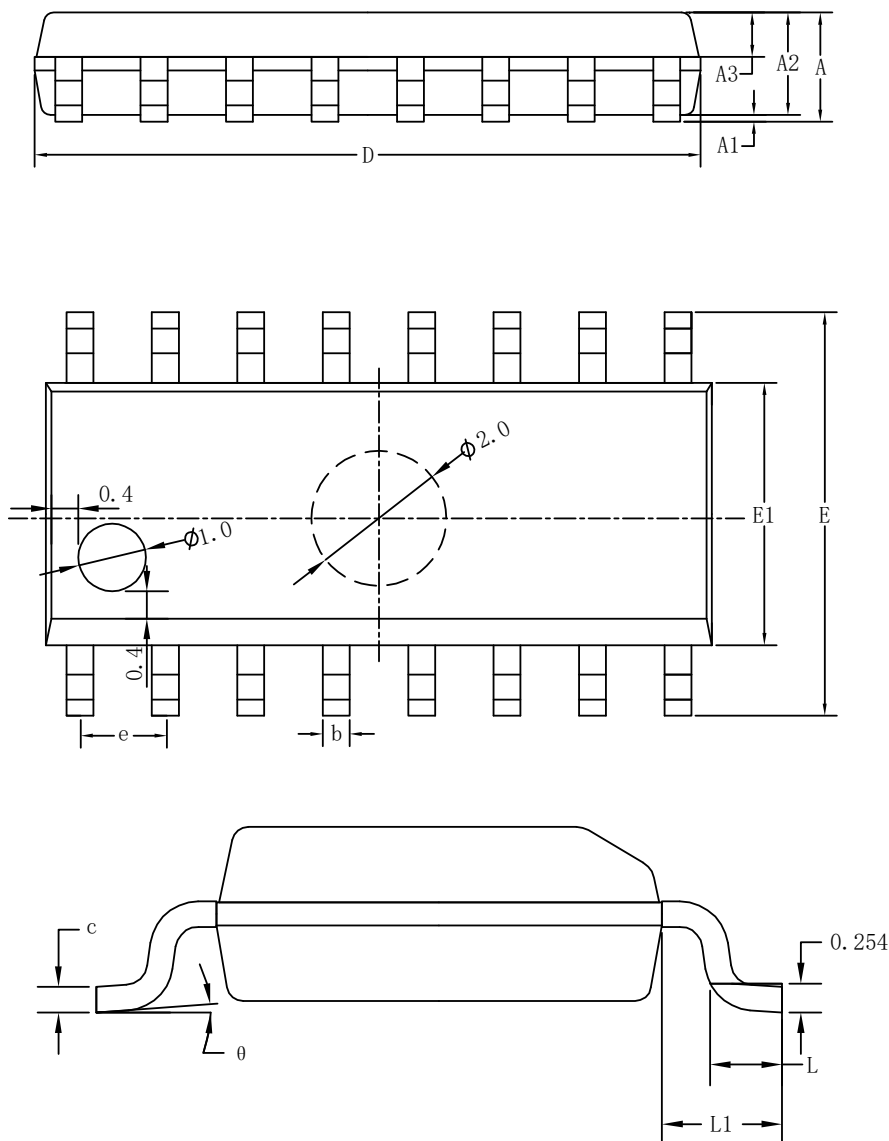
SOP-16



Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524 (BSC)		B1	0.060 (BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.80	19.20	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540 (BSC)		e	0.100 (BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354



SOP-16



Size Symbol	Dimensions In Millimeters			Size Symbol	Dimensions In Inches		
	Min (mm)	Nom (mm)	Max (mm)		Min (in)	Nom (in)	Max (in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e	1.27 (BSC)			e	0.050 (BSC)		
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1	1.05 (BSC)			L1	0.041 (BSC)		
θ	0°	4°	8°	θ	0°	4°	8°



Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.